

Zytel® HTN52G35HSL BK083

HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTN52G35HSL BK083 is a 35% glass reinforced, heat stabilized, lubricated high performance polyamide resin that can be molded in water heated molds. It is also a PPA resin.

General Information

Resin Identification ISO 1043

Density ISO 1183

PA6T/66-GF35

1460/- kg/m³

Drying

Drying Recommended

yes

Drying Temperature**

100 °C

Drying Time*

6 - 8 h

Processing Moisture Content - Optimum**

0.05 %

Processing Moisture Content

≤0.1 %

Temperature settings

Melt Temperature Optimum Internal

325 °C

Min. melt temperature***

320 °C

Max. melt temperature

330 °C

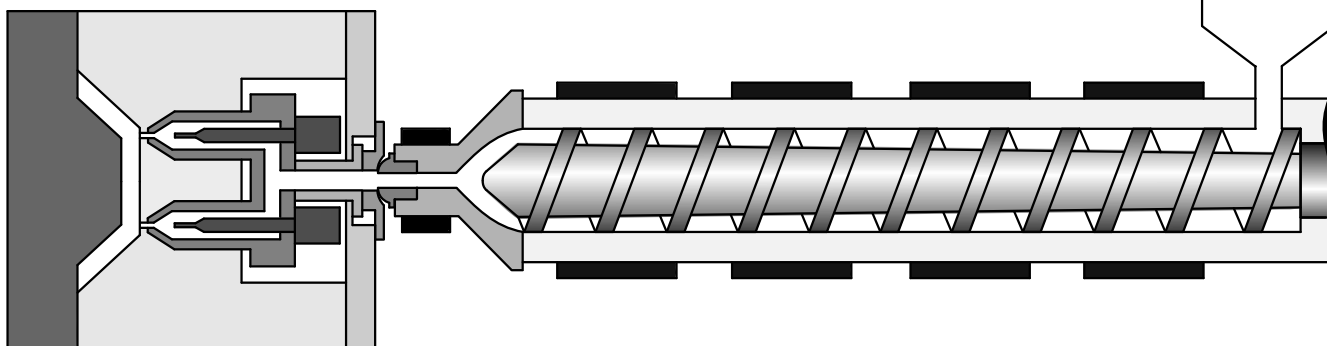
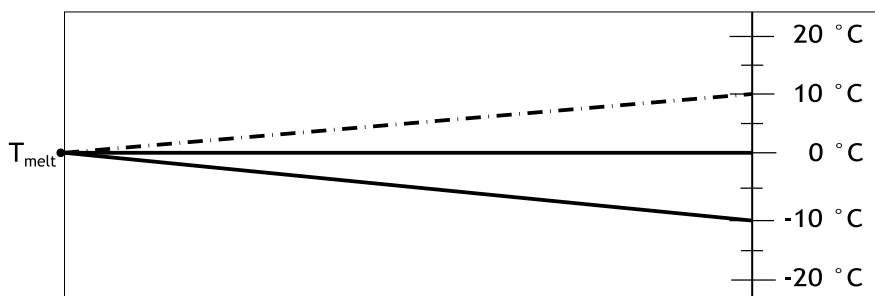
Min. mould temperature

90 °C

Max. mould temperature

110 °C

3 D (< 3 min)	----
2 D (3-5 min)	=====
1 D (> 5 min)	=====



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Recommended general settings

Residence time - optimum range	3 - 5 min
Residence time - maximum	10 min
Hold Pressure Time	$h^2 + 2 \text{ s}$
(h is the max. wall thickness of the part in mm)	

$$\text{Residence time} = \frac{8 \cdot \text{screw } \varnothing \text{ [mm]} \cdot \text{cycle time [s]}}{60 \cdot \text{dosing stroke [mm]}}$$

Hot runner residence time not included in calculation

Special precautions

During molding, use proper protective equipment and adequate ventilation. Avoid fumes and limit the residence time and temperature of the resin in the machine.

Links for further information

Trouble Shooting Guide

For further information e.g. on Shrinkage, Hot runner systems, Venting, Gating, Drying and moisture measurement, Regrind, Purging, please refer to the detailed Molding Guide.

Footnotes:

- * Improper storage may lead to longer drying times
- ** Excessive drying may lead to viscosity increase during processing. A discoloration of natural colored materials is possible.
- *** Using melt temperature lower than recommended could create unmelt, leading to weak parts